

Four characteristics of BM(D)



Excellent finish

Excellent finish for efficient outgassing even when heating for a short time.



Flux spattering prevention

Flux spattering prevention because of using special flux of rapid heating.



Excellent wettability

Flux spreads and excellent wettability in a perfect circular shape.



Prevention of burn in flux residue

There is no burn of the flux residue, for using high temperature resistant flux.

Appearance of finish

■Test condition

Semiconductor laser FOM-B454-S002 (Horiuchi Electronics Co., Ltd.) 15W 1.5sec







O No spattering

ltem	FLF01-BM(D)	Test standard
Alloy composition	Sn96.5%-Ag3.0%-Cu0.5%	JIS Z3282
Solidus temperature	Approx. 217℃	JIS Z3282
Liquidus temperature	Approx. 219℃	JIS Z3282
Particle size (TYPE4 • TYPE5)	22~38μm 15~25μm	JIS Z3284 (J-STD-005)
Flux content	13.00%	JIS Z3197
Halide content	0.05%	JIS Z3197
Viscosity	90Pa • s	JIS Z3284
Thixotropy index	0.65	JIS Z3284
Copper plate corrosion test	Pass	JIS Z3197
Insulation resistance test (85°C 85%RH 168hr)	> 5.0×10 ⁸ Ω	JIS Z3197
Migration test (85°C 85%RH 1,000hr)	Pass	JIS Z3197
Spread rate	88%	JIS Z3197

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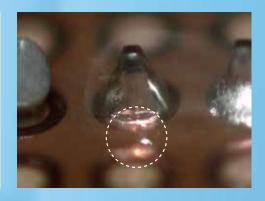


Void suppression



Voids are suppressed by efficiently discharging outgas and eliminating bubbles in the solder.





Comparison of solder wettability



There is no outflow of unmelted solder powder during rapid heating, which has a high aggregation effect.





Verification of flux residue

It has excellent high temperature resistant flux, so there is no burn in the flux residue.



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